

New Product: Microbond® DA5118 P Solvent Clean High-Lead Printing Solder Paste

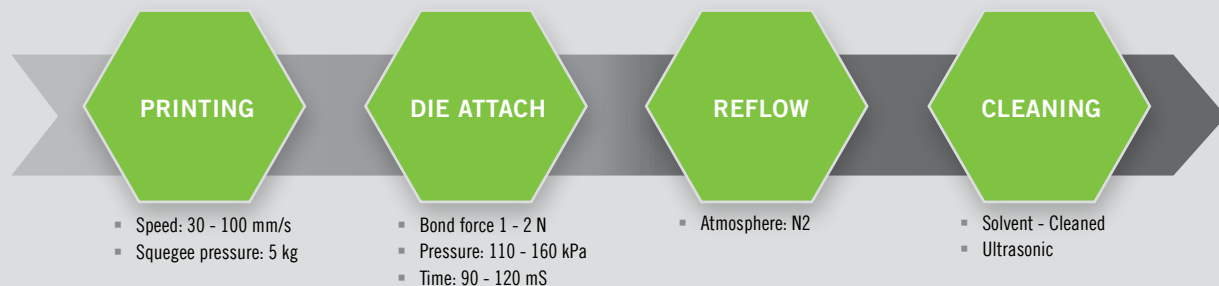
Microbond® DA5118 P is a high melting point solder paste for printing in die, clip and bridge applications. The paste exhibits stable rheology, excellent paste deposit, low void rates and easy cleanability to deliver a high-reliability joint. DA5118 P ease of handling offers the highest UPH for high volume production of leadframe devices. Spacer options guarantee bond-line control to meet increasing reliability requirements and address thinner dies packaging.

Microbond® DA5118 P Benefits

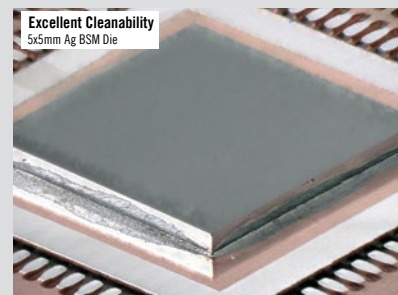
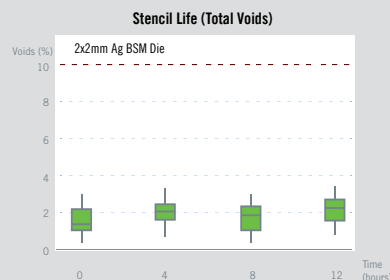
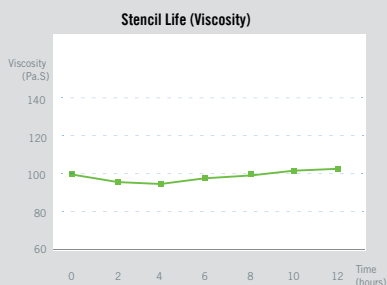
- Halogen zero
- Exceptional printing consistency
- Suitable for small to large dies
- Spacer option for bondline standoff
- Long work life
- Wide reflow temperature window
- Low void rates
- Excellent cleanability
- Enables higher throughput

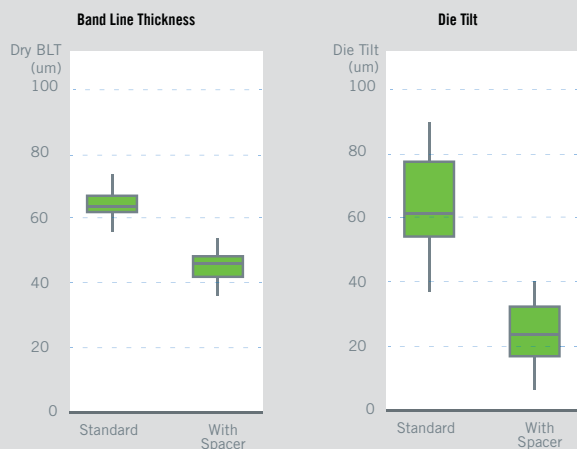


DA5118 P Solder Paste Process and Application



Continuous Printing Performance

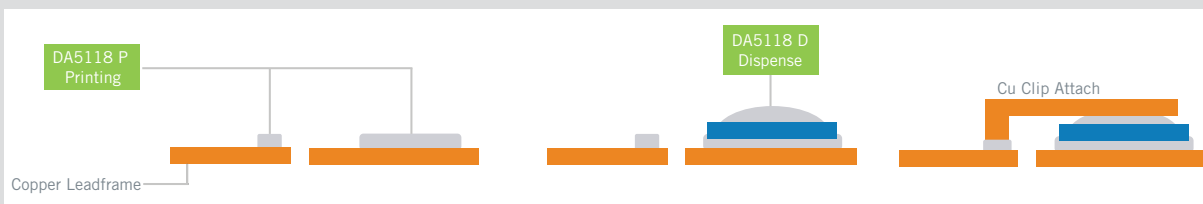


DA5118 P Spacer Option

Process Recommendation for Power Clip Attachment

Product Properties Table

Physical Properties	DA5118 P
Alloy	PbSn5Ag2.5
	PbSn5Ag2.5 + Spacers
	PbSn5
Metal Content	91 %
Halogen Content	Halogen zero
Flux Activity	ROLO
Application/Process	
Printing Speed	up to 150 mm/s
Reflow Temperature	360 - 390°C
Reflow Atmosphere	N2
Features & Benefits	
Cleaning	Solvent Clean
Work Life	≥ 12 hr
Shelf Life	4 mths
Storage Condition	2 - 10 °C

Process Recommendation for Power Clip Attachment

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